

ABSTRACT

In a first embodiment of the invention, an organic electronic device is encapsulated using an epoxy that includes a desiccant. The epoxy is around a perimeter of the organic electronic device. The epoxy bonds an encapsulation lid to a substrate and also absorbs oxygen and/or moisture. The desiccant in the epoxy is: barium oxide, calcium oxide, magnesium oxide, cobalt chloride, calcium chloride, calcium bromide, lithium chloride, zinc chloride, zinc bromide, sodium molecular, silicon dioxide, aluminum oxide, calcium sulfate, copper sulfate, potassium carbonate, magnesium carbonate, titanium dioxide, bentonite, acidic clay, montmorillonite, diatomaceous earth silica alumina, zeolite, silica, zirconia, activated carbon, or a mixture thereof.